EAST Text search notes

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L20	2	"5699611".pn. "6724084".pn.	US-PGPUB; USPAT	OR	ON	2006/01/06 15:27
L4	34	(US-20010022207-$ or US-20010055856-$ or US-20020106867-$ or US-20020113296-$ or US-20020119597-$ or US-20020163072-$ or US-20030000067-$ or US-20040011783-$ or US-20040014308-$ or US-20040016995-$ or US-20040066258-$ or US-20040104460-$ or US-20040188821-$).did. or (US-5241450-$ or US-5262351-$ or US-5401672-$ or US-5448014-$ or US-5455445-$ or US-5872025-$ or US-6238951-$ or US-6297072-$ or US-6306526-$ or US-6355501-$ or US-6373130-$ or US-6455353-$ or US-6461893-$ or US-6479320-$ or US-6518096-$ or US-6566745-$ or US-6596117-$ or US-6643920-$ or US-6645832-$ or US-6649444-$ or US-6697257-$).did.	US-PGPUB; USPAT	OR	ON	2006/01/06 15:27
L19	2650	(barrier or wall or seal or ring or guard) near6 (periphery or peripheral or outside or edge) near3 (wafer)	US-PGPUB; USPAT	OR	ON	2006/01/06 15:21
L18	138	(barrier or wall or seal or ring or guard) near5 (protection or protective or crack or cracking or contamination or contaminating or hermetic or corrosion) near10 (dicing or singulation or singulating or singulated or cleaving or cleavage or cleaved or sawing or scribing or scribed)	US-PGPUB; USPAT	OR	ON	2006/01/06 15:21
L17	6657	(barrier or wall or seal or ring or guard) near10 (dicing or singulation or singulating or singulated or cleaving or cleavage or cleaved or sawing or scribing or scribed)	US-PGPUB; USPAT	OR	ON	2006/01/06 15:10
L16	126	(barrier or wall or seal or ring or guard) near10 (wafer or die or substrate) near3 (thinning)	US-PGPUB; USPAT	OR	ON	2006/01/06 15:09
L15	716	438/462.ccls.	US-PGPUB; USPAT	OR	ON	2006/01/06 14:53
L12	743	438/458.ccls.	US-PGPUB; USPAT	OR	ON	2006/01/06 14:48
L14	42	438/458.ccls. and (hermetic$5 or peripheral or edge) near2 (seal$3)	US-PGPUB; USPAT	OR	ON	2006/01/06 14:47
L10	83	438/455.ccls. and (hermetic$5 or peripheral or edge) near2 (seal$3)	US-PGPUB; USPAT	OR	ON	2006/01/06 14:47
L13	105	438/458.ccls. and (barrier or seal or sealing or pillar or line or spacer or sealed) near5 (periphery or peripheral or perimeter or edge or outer or outside or hermetic$5)	US-PGPUB; USPAT	OR	ON	2006/01/06 14:39
L9	156	438/455.ccls. and (barrier or seal or sealing or pillar or line or spacer or sealed) near5 (periphery or peripheral or perimeter or edge or outer or outside or hermetic$5)	US-PGPUB; USPAT	OR	ON	2006/01/06 14:39
L11	245	438/456.ccls.	US-PGPUB; USPAT	OR	ON	2006/01/06 14:38
L8	103	438/108.ccls. and (hermetic$5 or peripheral or edge) near2 (seal$3)	US-PGPUB; USPAT	OR	ON	2006/01/06 14:18
L7	239	438/108.ccls. and (barrier or seal or sealing or pillar or line or spacer or sealed) near5 (periphery or peripheral or perimeter or edge or outer or outside or hermetic$5)	US-PGPUB; USPAT	OR	ON	2006/01/06 14:02
L6	91	438/107.ccls. and (hermetic$5 or peripheral or edge) near2 (seal$3)	US-PGPUB; USPAT	OR	ON	2006/01/06 13:29
L3	168	438/107.ccls. and (barrier or seal or sealing or pillar or line or spacer) near5 (periphery or peripheral or perimeter or edge or outer or outside)	US-PGPUB; USPAT	OR	ON	2006/01/06 13:17
L1	368	(wafer) near2 (scale or level) near6 (bond or bonding or attachment or attaching or bonded or attached or flip adj chip or chip-on-chip) and (barrier or corrosion or contamination or crack or sealing or seal or ridge or hermetic or hermetically) near10 (edge or periphery or peripheral or outside or outer or border or metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 12:48

S11 6	271	((die or wafer or chip or integrated adj circuit or ic) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip or chip-on-chip) and (barrier or corrosion or contamination or crack or sealing or seal or ridge or hermetic or hermetically) near3 (edge or periphery or peripheral or outside or outer or border) near3 (metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 11:31
S11 5	282	(wafer or substrate) near3 (edge or periphery or peripheral or outer or outside) near6 (ring or wall or spacer) near4 (metal or metallic or solder or tin or copper or cu or gold or au)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 10:55
S11 4	4	"5401672".pn. "20020163072"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 10:40
S11 2	263	(wafer or substrate) near (periphery or edge or peripheral or outer) near4 (barrier or spacer or ring or seal or sealing) same (wafer or substrate) near3 (stack or stacked or stacking or bonding or bonded or bond or 3d or "3-d" or three near dimensional)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 10:38
S30	210	(wafer or substrate) near (periphery or edge or peripheral or outer) near4 (barrier or spacer or ring or seal or sealing) same (wafer or substrate) near3 (stack or stacked or stacking or bonding or bonded or bond or 3d or "3-d" or three near dimensional)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 10:22
S11 1	129	(scribe or scribing or cleave or cleaving or singulating or singulation or dice or dicing) near8 (barrier or seal or sealed or sealing) near4 (hermetic$5)	US-PGPUB; USPAT	OR	ON	2006/01/06 10:11
S11 0	381	flip adj chip same (seal or sealing or sealed) near2 (hermetic$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 09:49
S10 9	491	(wafer near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (seal or sealing or sealed) near2 (hermetic$5) near10 (metal or metallic or copper or cu or gold or au or nickel or ni or platinum or pt)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 09:12
S8	340	(wafer near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (seal or sealing or sealed) near2 (hermetic$5) near10 (metal or metallic or copper or cu or gold or au or nickel or ni or platinum or pt)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 09:11
S10 8	49	"3648131".pn. "3705332".pn. "4897708".pn. "4954875".pn. "4998665".pn. "5045914".pn. "5229647".pn. "5283107".pn. "5404044".pn. "5510655".pn. "5608265".pn. "5640049".pn. "5717247".pn. "5751556".pn. "5825080".pn. "5901050".pn. "6391669".pn. "6593645".pn. "6608371".pn. "6661085".pn. "6882045".pn. "20010038148" "20020017710" "20020195673" "20030148596"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 09:02
S10 7	125	((die or wafer or chip or substrate) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (edge or periphery or peripheral or outside or outer) near3 (raised or elevated or projection or ridge) near10 (metal or metallic or aluminum or al or copper or cu or gold or au or silver or ag or nickel or ni)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 14:31
S5	107	((die or wafer or chip or substrate) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (edge or periphery or peripheral or outside or outer) near3 (raised or elevated or projection or ridge) near10 (metal or metallic or aluminum or al or copper or cu or gold or au or silver or ag or nickel or ni)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 14:29

S106	192	((die or wafer or chip) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (barrier or corrosion or contamination or crack or sealing or seal) near3 (edge or periphery or peripheral or outside or outer) near3 (metal or copper or cu or metallic or aluminum or gold or silver)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 14:17

EAST — Interference Search notes

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	66	((barrier or wall or seal or ridge) near4 (periphery or outer or outside or peripheral or edge or bead) near6 (wafer)).clm.	US-PGPUB	OR	ON	2006/01/06 16:38
L3	9	((barrier or wall or seal or ridge) near4 (periphery or outer or outside or peripheral or edge or bead) near8 (dicing or singulation or singulated or singulating or cleaving or cleave or cleavage or diced or scribing or scribed or sawing)).clm.	US-PGPUB	OR	ON	2006/01/06 16:39
L4	63	((barrier or wall or seal or ridge) near4 (periphery or outer or outside or peripheral or edge or bead) near15 (crack or cracking or contaminat$4 or corros$4)).clm.	US-PGPUB	OR	ON	2006/01/06 16:41
L6	8	((barrier or wall or seal or ridge) near10 concentric near4 (die or chip or wafer or ic)).clm.	US-PGPUB	OR	ON	2006/01/06 16:41
L7	2	((wafer) near2 (stack or stacked or bonding or bonded) and (barrier or ridge or seal or wall) near10 (thinning or thinned or singulated or singulation or cleaving or cleavage or cleaved or cleave or singulating or dicing or diced or scribing or scribed or scribe or sawing)).clm.	US-PGPUB	OR	ON	2006/01/06 16:43
L8	2	((wafer) near2 (scale) near10 (barrier or ridge or seal or wall or sealing or sealed)).clm.	US-PGPUB	OR	ON	2006/01/06 16:43